



Crossing Automation Introduces Wafer-Level Automation Engineering Services Offering

MOUNTAIN VIEW, Calif.—May 5, 2009—Crossing Automation, Inc., (www.crossinginc.com) today introduced its ExpressSolutions™ engineering services platform. With ExpressSolutions, the company's highly skilled engineering organization identifies and supports customer product and process requirements to deliver optimized wafer transfer platform solutions.

ExpressSolutions drives the implementation of Crossing's [ExpressConnect™](#) standard automation modules and subsystems by facilitating the design, system integration and maintenance of a complete wafer level automation system. This allows customers to leverage internal engineering while accessing ExpressConnect's reduced acquisition costs, reduced inventory build up and lowering support costs.

“Our true expertise is optimizing wafer-level automation. ExpressConnect, our hardware and software offering, is a byproduct of that expertise. ExpressSolutions is where our true value is best represented,” stated Larry Wise, Crossing's vice president of engineering. “ExpressSolutions allows us to deliver our experience with, and understanding of, the ExpressConnect components. We can take the demands placed on process tool manufacturers directly from the customer, in order to integrate their ideas with our modules. This allows us to achieve unique, fully supported platforms tailored to each customer's specific requirements.”

ExpressSolutions is focused on two primary service areas: system integration engineering and custom design engineering. Customers can use Crossing's system integration engineering to obtain a complete ExpressConnect system design, documentation package and sustaining engineering service along with custom engineered specials (CES) support including design, documentation and on-going support. With Crossing's custom design engineering services, customers have the ability to add their own proprietary content to the standard ExpressConnect modules to create fully customized platform solutions, along with a documentation package and sustaining engineering and CES support.

“Industry reception to the concept of a standardized, modular approach to wafer level transport as introduced with ExpressConnect earlier this year has been overwhelmingly positive,” said Larry Dulmage, vice president of marketing for Crossing Automation. “ExpressSolutions maximizes the benefits customers

can achieve from ExpressConnect by enabling them to design, recommend, build, test, deliver and support an automation system that directly addresses their specific wafer transfer requirements.”

ABOUT CROSSING AUTOMATION:

Crossing Automation delivers efficient, cost-effective integrated vacuum wafer handling systems and engineering support to high volume manufacturers of vacuum process tools, including etch, CVD, clean, RTP and metrology. Crossing’s ExpressSolutions engineering services offers system integration and custom design engineering to optimize wafer-level automation systems that implement the company’s ExpressConnect automation modules and subsystems. The company’s unique approach enables its customers to develop process-specific wafer transport solutions for multi-platform strategies at a significantly lower cost than current approaches. Offering an alternative to conventional “cluster tool” technology, Crossing achieves critical manufacturing flexibility for OEMs and IC manufacturers alike.

Company Contact:

Larry Dulmage

Crossing Automation

Tel: 650-210-8391

E-Mail: ldulmage@crossinginc.com

Agency Contact:

Amy Smith

Impress Public Relations

Tel: 401-369-9266

E-Mail: amy@impress-pr.com